

.075-.095
[1.91-2.41]

.034-.042
[0.86-1.07]

.005±.001 TYP
[0.13±0.02]
NOTE 2

PIN 1 IDENT
NOTE 3

.008-.012
[0.20-0.30]

.045 MAX TYP
[1.14]

.705 MAX
[17.91]

.005 MIN TYP
[0.12]

28

15

.250-.320 TYP
[6.35-8.13]

.335 MAX
[8.51]

.250-.320 TYP
[6.35-8.13]

1

14

.017±.002 TYP
[0.43±0.05]
NOTE 2

.050±.005 TYP
[1.27±0.12]

CONTROLLING DIMENSION IS INCH
VALUES IN [] ARE MILLIMETERS

NOTES: UNLESS OTHERWISE SPECIFIED

1. LEAD FINISH: SOLDER DIPPED WITH Sn60 OR Sn63
SOLDER CONFORMING TO A MINIMUM THICKNESS
OF 200 MICROINCHES/ 5.08 MICROMETERS.
SOLDER MAY BE APPLIED OVER LEAD BASIS METAL OR Sn PLATE.
2. LEAD THICKNESS MAY BE INCREASED BY .003 INCHES/ 0.08 MILLIMETERS
MAXIMUM AFTER LEAD FINISH APPLIED.
3. LEAD 1 IDENTIFICATION SHALL BE:
a) A NOTCH OR OTHER MARK WITHIN THIS AREA
b) A TAB ON LEAD 1, EITHER SIDE
4. REFERENCE JEDEC REGISTRATION MO-019, VARIATION AD, DATED 9/20/77.

REVISIONS

LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
D	REVISE AND REDRAW PER CURRENT STANDARD; UPDATE TITLE & MIL/AERO STAMP.	11047	07/14/95	MS/

MIL-PRF-38535
CONFIGURATION CONTROL

APPROVALS		DATE		 National Semiconductor 2900 Semiconductor dr., Santa Clara, CA 95052-8090				
DRAWN <i>MARTA SUCHY</i>		07/14/95						
DFTG. CHK.								
ENGR. CHK.								
 PROJECTION INCH [MM]				SCALE		SIZE	DRAWING NUMBER	REV
				N/A		C	MKT-W28A	D
DO NOT SCALE DRAWING						SHEET 1 of 1		